



Flexible and Printed Electronics

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Message from the Guest Editors

Dear Colleagues,

Foldable and bendable devices have been commercialized, and the flexible electronics market has been rapidly expanded. Accordingly, flexible electronics have been considered as the next paradigm following the smartphone. Flexible and printed electronics have been significantly developed over the last two decades, from conductive films to biomedical products. However, there are still many scientific and engineering obstacles blocking the complete paradigm shift to flexible electronics.

This Special Issue aims to bring together the latest innovative advances in the materials, processes, and applications of flexible and printed electronics.

Topics for this Special Issue include, but are not limited to, the following topics:

- Synthesis of organic and inorganic materials;
- Flexible and printed electronics;
- Stretchable electronics;
- Bioelectronics and biosensors;
- Coating and printing;
- Roll-to-roll manufacturing;
- Reliability in flexible and printed devices;
- Artificial intelligence in flexible and printed devices.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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